

2018 IMAPS Nordic Conference on Microelectronics Packaging (NordPac 2018)

**Oulu, Finland
12-14 June 2018**



**IEEE Catalog Number: CFP18M25-POD
ISBN: 978-1-5386-8019-3**

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|-------------------------|-------------------|
| IEEE Catalog Number: | CFP18M25-POD |
| ISBN (Print-On-Demand): | 978-1-5386-8019-3 |
| ISBN (Online): | 978-952-68150-5-3 |

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| | |
|---|-----------|
| <i>Processing of printed silver patterns on an ETFE substrate</i> Riikka Mikkonen, Sanna Lahokallio, Laura Frisk and Matti Mäntysalo | 1 |
| <i>Contribution to non-destructive inspection of power semiconductor assemblies by stimulating a lateral heat flow</i> Michael Schaulin, Ulrich Nordmeyer, Martin Oppermann and Thomas Zerna | 8 |
| <i>Quality assurance of encapsulation architecture, including subsequent washing process for permanently mounted wearable sensors</i> Heléne Karlsson, Oscar Lidström, Hans Grönqvist, Dag Andersson, Jan Wipenmyr and Niina Hernandez | 14 |
| <i>Overcoming Human Factors by Utilizing Design Modeling to Improve High Reliability Electronics</i> Greg Caswell, Natalie Hernandez, Nathan Blattau and Craig Hillman | 24 |
| <i>Plastic QFN Packaging for Space Applications</i> Ignas van Dommelen , Barbara Bonnet, Marc Feron, Vladimir Cherman, Daniel Aguinaga and Mario Gonzalez | 29 |
| <i>Screen Printed Conductive Composites with Reduced Graphene Oxide and Silver</i> Man Song, Jie Zhao, Helena Grennberg and Zhi-Bin Zhang | 35 |
| <i>Electrical and Thermal Conduction of Isotropic Conductive Adhesive based on Novel Conductive Particles</i> Helge Kristiansen, Susanne Helland, Erik Kalland, Mohamad Abo Ras and Corinna Grosse | 40 |
| <i>Improving the performance of advertising LED displays by in-mould integration</i> Eveliina Juntunen, Vishal Gandhi, Satu Ylimaulaand and Arttu Huttunen | 45 |

| | |
|--|-----------|
| <i>Component Packages for IMSETM (Injection Molded Structural Electronics)</i> Tomi Simula, Paavo Niskala, Mikko Heikkinen and Outi Rusanen | 50 |
| <i>Overload-proof LTCC differential pressure sensors for high temperature applications</i> Adrian Goldberg, Birgit Manhica, Steffen Ziesche and Uwe Partsch | 55 |
| <i>LTCC Resistors – The Influence of Production Conditions on the Absolute Value and its Reproducibility</i> Peter Uhlig, Alexandra Serwa, Jens Müller, Nam Gutzeit, Dieter Schwanke and Jürgen Pohlner | 61 |
| <i>Corrosion Reliability of Lead-Free Solder Systems Used in Electronics</i> Feng Li, Vadimas Verdingovas, Kai Dirscherl, Bálint Medgyes and Rajan Ambat | 67 |
| <i>Water film formation on the PCBA surface and failure occurrence in electronics</i> Kamila Piotrowska, Morten S. Jellesen and Rajan Ambat | 72 |
| <i>Multifunctional MMICs – Key Enabler for Future AESA Panel Arrays</i> Martin Oppermann and Ralf Rieger | 77 |
| <i>Wafer-level Re-Packaging of Commercial Components for Miniaturization and Embedding</i> Jens Müller, Markus Hülsmann, Nam Gutzeit and Michael Fischer | 81 |
| <i>A Printed Electroluminescent Matrix Display: Implementation Details and Technical Solutions</i> Artem Ivanov | 86 |
| <i>Reliability study on high thermally conductive graphene film as heat spreader in electronics cooling applications</i> Amos Nkansah, Nan Wang, Lilei Ye, Xitao Wang and Johan Liu | 95 |